

Base Station

EMI Shielding + Thermal Management

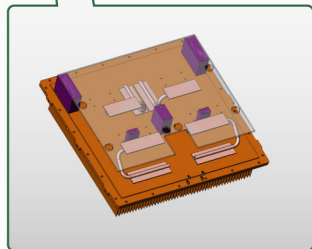
▼ Wimax



▲ Form-In-Place Elastomers (FIPG)

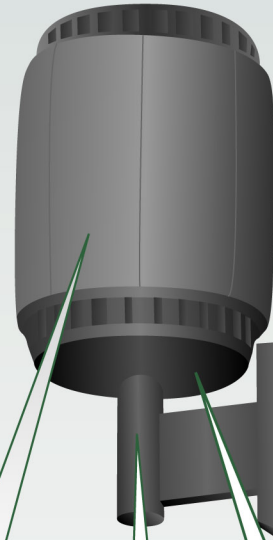


▲ Conductive Elastomers

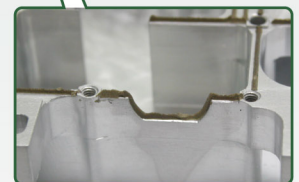


▲ Thermal Module/
Gap Fillers/
Silicone Grease

▼ Scalable Wide-Area Wi-Fi



▲ Insulative Silicone
Cushion Gasket.



▲ AI CNC Milling/FIPG



▲ Plastic Clamshell Covers

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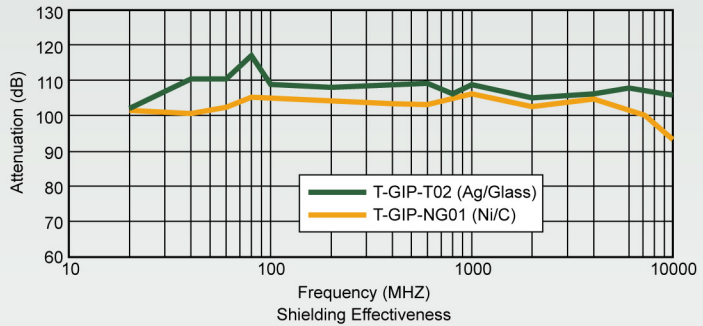
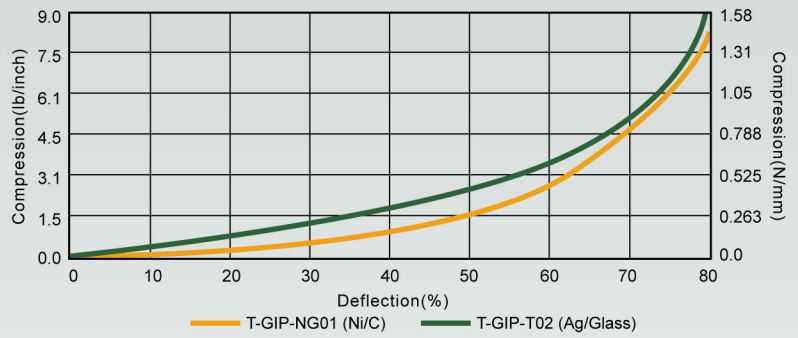
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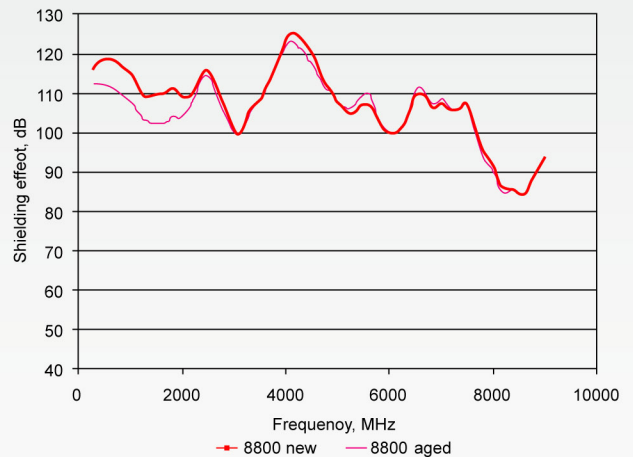
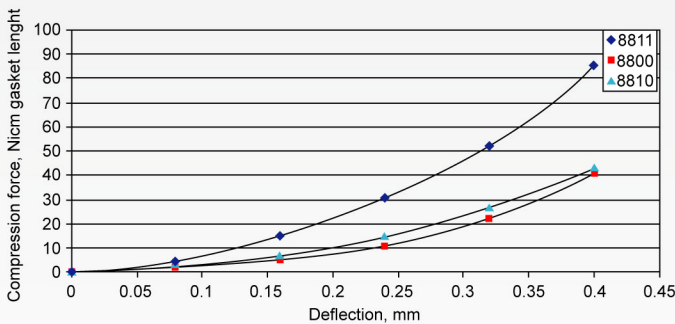
Conductive Elastomers

PartNo.	T-GIP-NG01	T-GIP-T02	T-GIP-T03
filler	Ni/C	Ag/Glass	Ag/Cu
Shielding	>100	80-100	80-105
Compression Set%	30	35	32

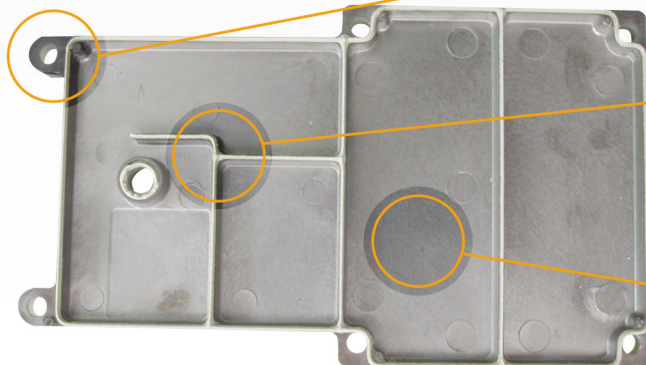


Form-In-Place Gasket (FIPG Tri-Shield)

Sample	8800	8810	8811
Filler	Ag / Ni	Ni / C	Ni / C
Height	1.0 - 3.0 mm	1.0 - 3.0 mm	1.0 - 3.0 mm
Compression Set %	25	40	45



Plastic Clamshell Can (Pcan)



Plastic Housing

- Max Temp 70-150 Deg C
- ABS, PCABS, PA, PPA, PPS
- Rigid

Conductive Silicon Gasket

- Robotic Placement for repeatability
- Highly conductive for superior shielding
- Minimum contact width of .3mm
- Grounds to PCB

Physical Vapor Deposition

- Copper/NiCr coating
- Excellent adhesion and conformity